IPC ASSOCIATION CONNECT ELECTRONICS INDUSTR	Material Comp © Copyright 2005. Il international and Par	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				erials and N	ials and Mfg Information				
upplier Infor	mation														
Company name*			Company unique ID			τ	Unique ID Authority				Respon	Response Date*			
onsemi											2025-00	2025-06-07			
Contact Name			Title - Contact			1	Phone - Contact*				Email ·	Email - Contact*			
Product-Env-Stewards			Product Enviro Compliance				NA				Produ	Product-Env-Stewards@onsemi.com			
Authorized Representative*			Title - Representative			1	Phone - Representative*				Email ·	Email - Representative*			
Product-Env-Stewards			Product Enviro Compliance				NA				Produ	Product-Env-Stewards@onsemi.com			
Reques	ter Item Number	Mfr Item Number		Mfr Item Name			Effective Date	e Versi	ion	Manufacturing Site		Weight*	UOM	Unit Type	
		FQB12P2	QB12P20TM QF -200V 470		mOhm D2PAK		2025-06-07 CPA		СРА	1485.9		mg	Each		
Ianufacturing	g Proccess Information	tion						,							
Terminal Plating / Grid Array Material T			Ferminal Base Alloy J-STD-020 MSI		SL Rating	Peak Process Body Temperature Max T		ire Max Time at Pea	ık Tempera	ture Numb	er of Reflow Cyc	eles			
Matte Tin (Sn) - annealed		CU Alloy 1			245 C		30	seco	nds 3						
omments															
vel 1 - maximum	time at peak temperatu	ire during sol	dering is 10-3	30 seconds											
or more informa	tion regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and cornect to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to su										
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature Ra	astislav Drska	-En								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	12.3	mg	Supplier	Silicon (Si)	7440-21-3		12.3	mg
Die Attach Solder	7.33	mg	Supplier	Silver (Ag)	7440-22-4		0.1832	mg
			A	Lead (Pb)	7439-92-1	7a	6.7803	mg
			Supplier	Tin (Sn)	7440-31-5		0.3665	mg
Lead Frame	860.32	mg	Supplier	Tin (Sn)	7440-31-5		1.0324	mg
			В	Nickel (Ni)	7440-02-0		0.4302	mg
			Supplier	Copper (Cu)	7440-50-8		858.8575	mg
Mold Compound-Black	595.8	mg	Supplier	Brominated Epoxy Resin-2	68541-56-0		14.895	mg
			Supplier	Other Epoxy resins	Proprietary Data		17.874	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		11.916	mg
			Supplier	Carbon Black (C)	1333-86-4		2.979	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		518.346	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		29.79	mg
Plating	5.52	mg	Supplier	Tin (Sn)	7440-31-5		5.52	mg
Wire Bond - Al	4.63	mg	Supplier	Aluminum (Al)	7429-90-5		4.63	mg